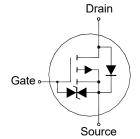
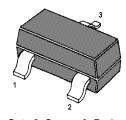
P-Channel Enhancement Mode MOSFET

Features

- · Advanced trench cell design
- Built-in G-S Protection Diode
- Typical ESD Protection HBM Class 2

Classification	Voltage Range(V)
0A	< 125
0B	125 to < 250
1A	250 to < 500
1B	500 to < 1000
1C	1000 to < 2000
2	2000 to < 4000
3A	4000 to < 8000
3B	≥ 8000





1. Gate 2. Source 3. Drain SOT-23 Plastic Package

Applications

- Portable applications
- · battery management

Absolute Maximum Ratings(at Ta = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	-V _{DS}	30	V
Gate-Source Voltage	V _G s	± 20	V
Continuous Drain Current	-I _D	6	Α
Pulsed Drain Current 1)	-I _{DM}	30	А
Total Power Dissipation 2)	P _{tot}	1.4	W
Operating Junction and Storage Temperature Range	TJ, Tstg	- 55 to + 150	°C

Thermal Characteristics

Parameter	Symbol	Max.	Unit	
Thermal Resistance from Junction to Ambient 2)	Reja	89	°C/W	

 $^{^{1)}}$ Pulse Test: Pulse Width ≤ 100 μs, Duty Cycle ≤ 2%,Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ =150°C.



²⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air

MKA03P043LK

Characteristics at Ta = 25°C unless otherwise specified

Parameter	Symbol	Min.	Тур.	Max.	Unit
STATIC PARAMETERS			1	<u> </u>	
Drain-Source Breakdown Voltage at -I _D = 250 μA	-V _{(BR)DSS}	30	-	-	V
Zero Gate Voltage Drain Current at -V _{DS} = 24 V	-I _{DSS}	-	-	1	μA
Gate-Source Leakage at $V_{GS} = \pm 16 \text{ V}$	lgss	-	-	± 10	μA
Gate-Source Threshold Voltage at V_{DS} = V_{GS} , I_D = 250 μ A	-V _{GS(th)}	1	-	2	V
Drain-Source On-State Resistance at -V _{GS} = 10 V, -I _D = 6 A at -V _{GS} = 4.5 V, -I _D = 5 A	R _{DS(on)}	- -	-	36 43	mΩ
DYNAMIC PARAMETERS					
Forward Transconductance at -V _{DS} = 5 V, -I _D = 6 A	gfs	-	7.3	-	S
Gate Resistance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	Rg	-	93	-	Ω
Input Capacitance at $-V_{DS} = 15 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	C _{iss}	-	755	-	pF
Output Capacitance at - V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHz	Coss	-	92	-	pF
Reverse Transfer Capacitance at $-V_{DS}$ = 15 V, V_{GS} = 0 V, f = 1 MHz	C _{rss}	-	83	-	pF
Total Gate Charge at -V _{DS} = 15 V, -V _{GS} = 10 V, -I _D = 6 A at -V _{DS} = 15 V, -V _{GS} = 4.5 V, -I _D = 6 A	Qg	- -	15.4 7.5	- -	nC
Gate to Source Charge at $-V_{DS} = 15 \text{ V}$, $-V_{GS} = 10 \text{ V}$, $-I_D = 6 \text{ A}$	Q _{gs}	-	2.9	-	nC
Gate to Drain Charge at - V_{DS} = 15 V, - V_{GS} = 10 V, - I_D = 6 A	Q _{gd}	-	3.2	-	nC
Turn-On Delay Time at -V _{GS} = 10 V, -V _{DS} = 15 V, -I _D = 6 A, R _g = 3.3 Ω	t _{d(on)}	-	65	-	nS
Turn-On Rise Time at -V _{GS} = 10 V, -V _{DS} = 15 V, -I _D = 6 A, R _g = 3.3 Ω	t _r	-	44	-	nS
Turn-Off Delay Time at -V _{GS} = 10 V, -V _{DS} = 15 V, -I _D = 6 A, R _g = 3.3 Ω	t _{d(off)}	-	52	-	nS
Turn-Off Fall Time at -V _{GS} = 10 V, -V _{DS} = 15 V, -I _D = 6 A, R _g = 3.3 Ω	t _f	-	18	-	nS
Body-Diode PARAMETERS					
Body Diode Voltage at -I _S = 1 A, V _{GS} = 0 V	-V _{SD}	-	-	1.2	V
Body-Diode Continuous Current	-Is	-	-	6	Α
Body Diode Reverse Recovery Time at $-I_S = 6$ A, di/dt = 100 A / μ s	t _{rr}	-	10.5	-	ns
Body Diode Reverse Recovery Charge at $-I_S = 6$ A, di/dt = 100 A / μ s	Qrr	-	4.2	-	nC



Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

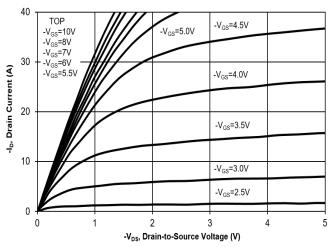


Fig. 2 Typical Transfer Characteristics

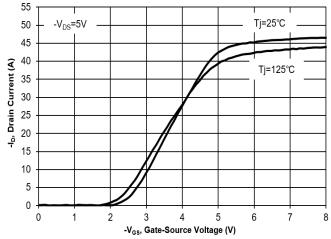


Fig. 3 On-Resistance vs. Drain Current

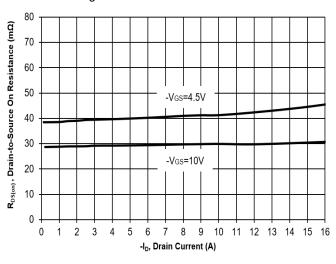


Fig. 4 On-Resistance vs. Gate-Source Voltage

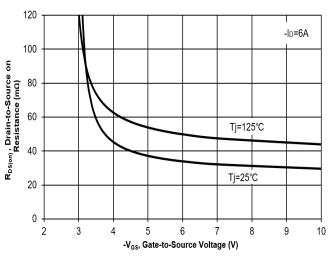


Fig. 5 On-Resistance vs.T_j

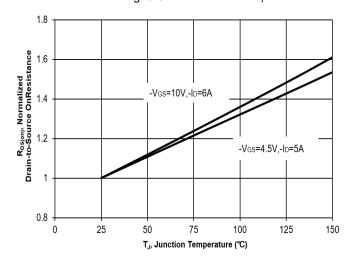
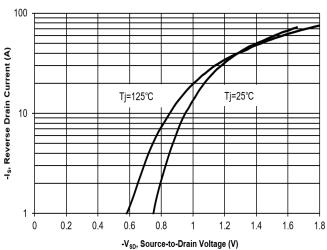


Fig. 6 Typical Body-Diode Forward Characteristics





Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

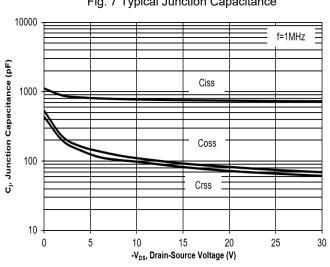


Fig. 8 Drain-Source Leakage Current vs. Tj

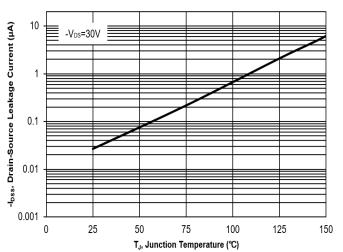


Fig. 9 $V_{(BR)DSS}$ vs. Junction Temperature

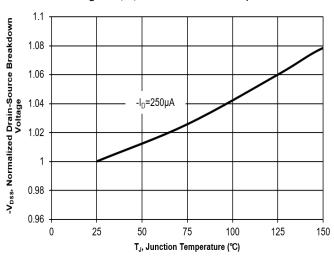


Fig. 10 Gate Threshold Variation vs. T_j

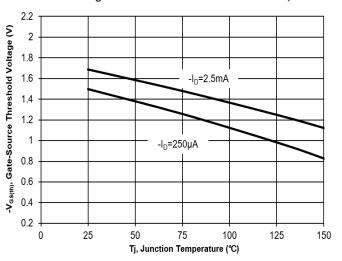
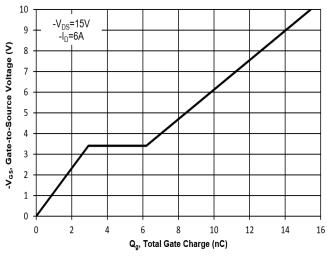
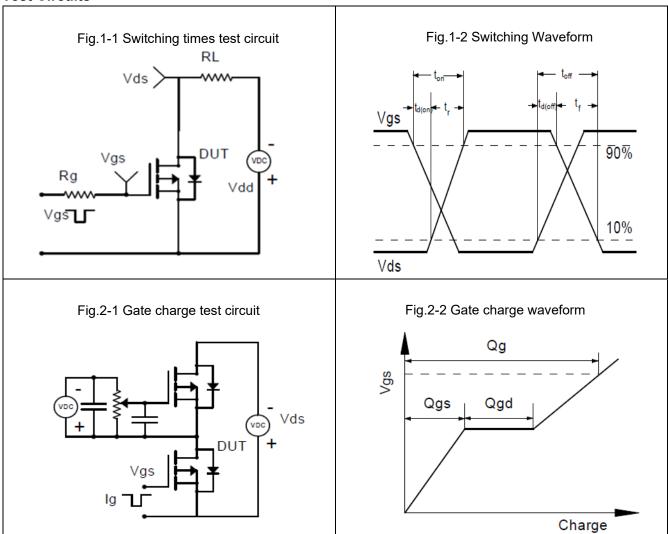


Fig. 11 Gate Charge





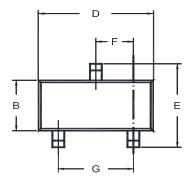
Test Circuits

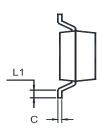


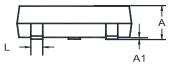


Package Outline (Dimensions in mm)

SOT-23

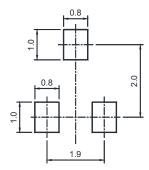






Unit	Α	A1	В	С	D	E	F	G	L	L1
	1.20	0.100	1.40	0.19	3.04	2.6	1.02	2.04	0.51	0.2
mm	0.89	0.013	1.20	0.08	2.80	2.2	0.89	1.78	0.37	MIN

Recommended Soldering Footprint



Packing information

Tape Width		Pit	tch	Reel	Size	
Package	(mm)	mm	inch	mm	inch	Per Reel Packing Quantity
SOT-23	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

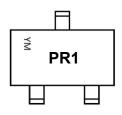
" PR1 " = Part No.

" YM " = Date Code Marking

" Y " = Year

" M " = Month

Font type: Arial



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